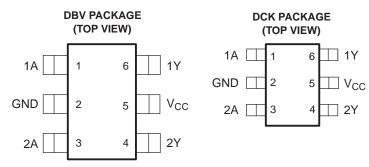
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DUAL SCHMITT-TRIGGER INVERTER

FEATURES

- Qualified for Automotive Applications
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 5.4 ns at 3.3 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C

- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} Feature Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

This dual Schmitt-trigger inverter is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC2G14 contains two inverters and performs the Boolean function $Y = \overline{A}$. The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION(1)

T _A	PACKAG	E ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING (3)
40°C to 95°C	SOT (SOT-23) - DBV	Tape and reel	SN74LVC2G14IDBVRQ1	C14_
–40°C to 85°C	SOT (SC-70) - DCK	Tape and reel	SN74LVC2G14IDCKRQ1	CF_

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(3) DBV/DCK: The actual top-side marking has one additional character that designates the wafer fab/assembly site.



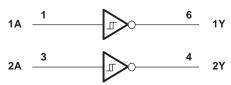
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FUNCTION TABLE (EACH INVERTER)

INPUT A	OUTPUT Y
Н	L
L	Н

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedance	e or power-off state (2)	-0.5	6.5	V
Vo	Voltage range applied to any output in the high or low stat	e ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
IO	Continuous output current			±50	mA
	Continuous current through V _{CC} or GND			±100	mA
0	Package thermal impedance (4)	DBV package		165	°C/W
θ_{JA}	Раскаде пеннантреоапсе 19	DCK package		259	- C/VV
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The value of V_{CC} is provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

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Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V	Cupply voltage	Operating	1.65	5.5	V
V _{CC}	Supply voltage	Data retention only	1.5		V
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V _{CC}	V
		V _{CC} = 1.65 V		-4	
	$\begin{aligned} & V_{\text{CC}} = 2. \\ & V_{\text{CC}} = 3 \end{aligned}$ High-level output current	V _{CC} = 2.3 V		-8	
I _{OH}		V 2V		-16	mA
		V _{CC} = 3 V		-24	
		V _{CC} = 4.5 V		-32	
		V _{CC} = 1.65 V		4	
	$V_{CC} = 2.3 \text{ V}$	V _{CC} = 2.3 V		8	
I _{OL}	Low-level output current	V 2V		16	mA
		$V_{CC} = 3 V$		24	
			32		
T _A	Operating free-air temperature		-40	85	°C

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN TYP(1)	MAX	UNIT
		1.65 V	0.7	1.4	
V _{T+}		2.3 V	1	1.7	
Positive-going		3 V	1.3	2.2	V
input threshold voltage		4.5 V	1.9	3.1	
		5.5 V	2.2	3.7	
		1.65 V	0.3	0.7	
V _T		2.3 V	0.4	1	
Negative-going		3 V	0.6	1.3	V
input threshold voltage		4.5 V	1.1	2	
		5.5 V	1.4	2.5	
		1.65 V	0.3	0.8	
ΔV_{T}		2.3 V	0.4	0.9	
Hysteresis		3 V	0.4	1.1	V
$(V_{T+} - V_{T-})$		4.5 V	0.6	1.3	
		5.5 V	0.7	1.4	
	$I_{OH} = -100 \mu A$	1.65 V to 4.5 V	V _{CC} - 0.1		
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2		
N/	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9		V
V _{OH}	I _{OH} = -16 mA	3 V	2.4		V
	I _{OH} = -24 mA	3 V	2.3		
	I _{OH} = -32 mA	4.5 V	3.8		
	I _{OL} = 100 μA	1.65 V to 4.5 V		0.1	
	I _{OL} = 4 mA	1.65 V		0.45	
N/	I _{OL} = 8 mA	2.3 V		0.3	V
V _{OL}	I _{OL} = 16 mA	3 V		0.4	V
	I _{OL} = 24 mA	3 V		0.55	
	I _{OL} = 32 mA	4.5 V		0.55	
I _I A inputs	V _I = 5.5 V or GND	0 to 5.5 V		±5	μΑ
l _{off}	V_I or $V_O = 5.5 \text{ V}$	0		±10	μΑ
I _{CC}	$V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$	1.65 V to 5.5 V		10	μΑ
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 5.5 V		500	μΑ
C _i	V _I = V _{CC} or GND	3.3 V	4		pF

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} = 2 ± 0.2		V _{CC} = ± 0.3		V _{CC} = ± 0.5		UNIT
	(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	Α	Y	3.9	9.5	1.9	5.7	2	5.4	1.5	4.3	ns

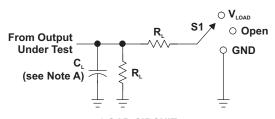
Operating Characteristics

 $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	V _{CC} = 5 V	UNIT	
	FARAMETER	TEST CONDITIONS	TYP TYP		TYP	TYP	UNIT	
C_{pd}	Power dissipation capacitance	f = 10 MHz	16	17	18	21	pF	



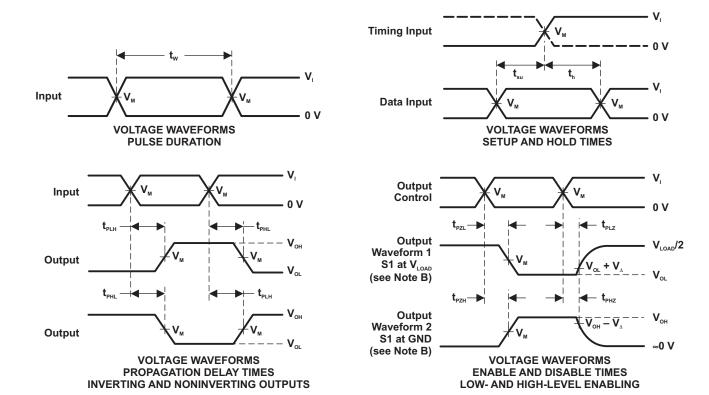
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t_{PLZ}/t_{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

	CIRC	шт
LUAD	CIRC	UII

		PUTS		v			.,
V _{cc}	V,	t,/t,	V _M	V _{LOAD}	C _L	R _⊾	V _A
1.8 V ± 0.15 V	V _{cc}	≤2 ns	V _{cc} /2	2 × V _{cc}	30 pF	1 k Ω	0.15 V
$2.5~V~\pm~0.2~V$	V _{cc}	≤2 ns	V _{cc} /2	2 × V _{cc}	30 pF	500 Ω	0.15 V
3.3 V ± 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V ± 0.5 V	V _{cc}	≤2.5 ns	V _{cc} /2	2 × V _{cc}	50 pF	500 Ω	0.3 V



NOTES: A. C, includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{o} = 50 Ω .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and \dot{t}_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. $t_{\mbox{\tiny PLH}}$ and $t_{\mbox{\tiny PHL}}$ are the same as $t_{\mbox{\tiny pd}}.$
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



24-Jan-2013

PACKAGING INFORMATION

Orderable Device		Package Type	U	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
SN74LVC2G14IDCKRQ1	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CFO	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF SN74LVC2G14-Q1:

Catalog: SN74LVC2G14

NOTE: Qualified Version Definitions:





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• Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

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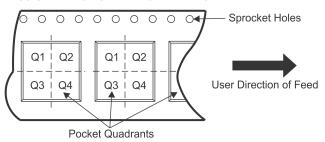
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

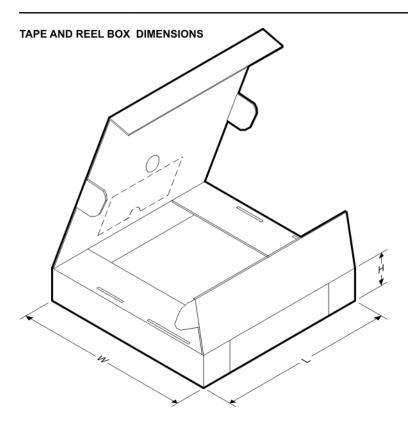
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC2G14IDCKRQ1	SC70	DCK	6	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3

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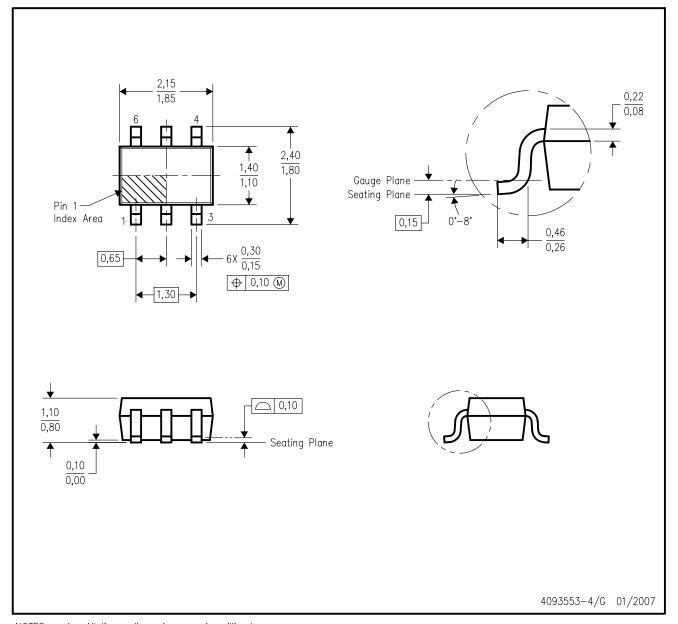


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LVC2G14IDCKRQ1	SC70	DCK	6	3000	203.0	203.0	35.0	

DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



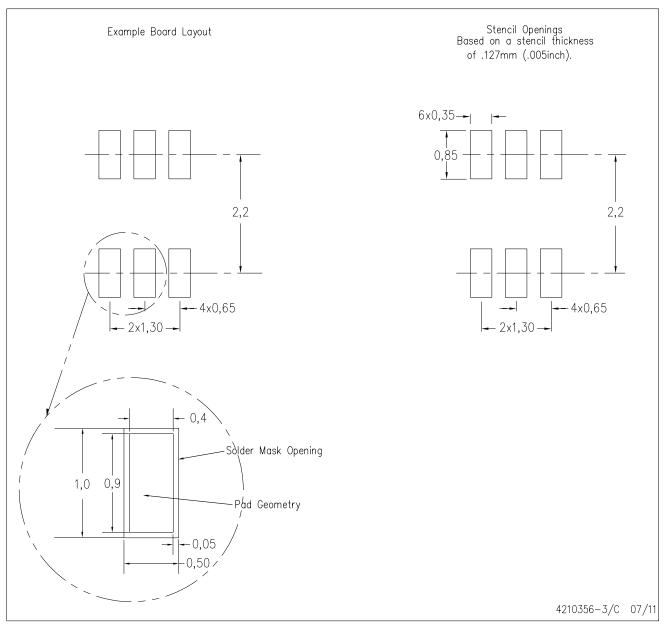
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AB.



DCK (R-PDSO-G6)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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> Sales:

Direct +86 (21) 6401-6692

Email amall@ameya360.com

QQ 800077892

Skype ameyasales1 ameyasales2

Customer Service :

Email service@ameya360.com

Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com